

6-Channel White LED Driver with Integrated FET for up to 60 LEDs

BD6590MUV

General Description

BD6590MUV is white LED driver IC with PWM step-up DC/DC converter that can boost max 40V and current driver that can drive max 30mA. The wide and precision brightness can be controlled by external PWM pulse.

BD6590MUV has very accurate current drivers, and it has few current errors between each strings. So, it will be helpful to reduce brightness spots on the LCD.

Small package type is suited for saving space.

Features

- High accuracy & good matching current drivers (MAX30mA/ch)
- Integrated 50V power Nch MOSFET
- Soft start
- Drive up to 10 in series 6strings in parallel
- Rich safety functions
 - Over-voltage protection
 - Over current limit
 - LED terminal open/short protect
 - External SBD open detect / Output short protection
 - UVLO
 - Thermal shutdown

Typical Application Circuit

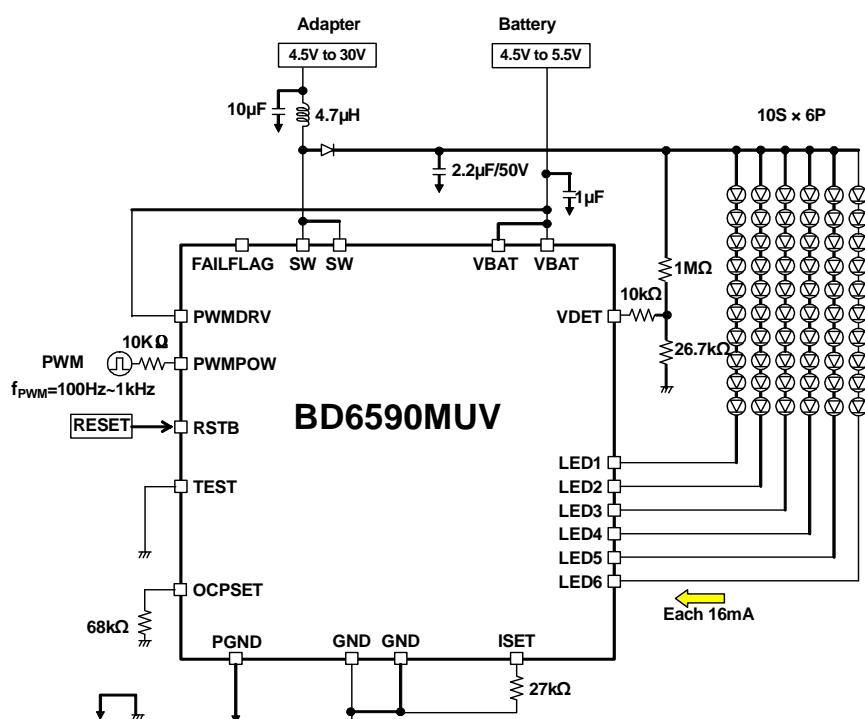


Figure 2. Typical Application Circuit

Key Specifications

- Operating power supply voltage range: 4.5V to 5.5V
- LED maximum current: 30mA (Max.)
- Switching frequency: 1.25MHz(Typ.)
- Quiescent Current: 0.1μA (Typ.)
- Operating temperature range: -40°C to +85°C

Package



VQFN024V4040
4.00mm x 4.00mm x 1.00mm

Figure 1.

Applications

All middle size LCD equipments backlight of Notebook PC, NetPC, portable DVD player, DPF, etc.

● Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Ratings		Unit	Condition
Terminal voltage 1	VMAX1	7		V	VBAT, ISET, TEST, RSTB, PWMDRV PWMPWR, VDET, FAILFLAG, OCPSET
Terminal voltage 2	VMAX2	25		V	LED1, LED2, LED3, LED4, LED5, LED6
Terminal voltage 3	VMAX3	41		V	SW
Power dissipation 1	Pd1	500		mW	*1
Power dissipation 2	Pd2	780		mW	*2
Power dissipation 3	Pd3	1510		mW	*3
Operating temperature range	Topr	-40 to +85		°C	-
Storage temperature range	Tstg	-55 to +150		°C	-

*1 Reduced 4.0mW/°C With Ta>25°C when not mounted on a heat radiation Board.

*2 1 layer (ROHM Standard board) has been mounted. Copper foil area 0mm², When it's used by more than Ta=25°C, it's reduced by 6.2mW/°C.

*3 4 layer (JEDEC Compliant board) has been mounted. Copper foil area 1layer 6.28mm², Copper foil area 2 to 4layers 5655.04mm², When it's used by more than Ta=25°C, it's reduced by 12.1mW/°C.

● Recommended Operating Rating (Ta=-40°C to +85°C)

Parameter	Symbol	Limits			Unit	Condition
		Min.	Typ.	Max.		
Power supply voltage	VBAT	4.5	5.0	5.5	V	

● Electrical Characteristics

(Unless otherwise specified, VBAT=5V, Ta = +25°C)

Parameter	Symbol	Limits			Unit	Condition
		Min.	Typ.	Max.		
Quiescent current	Iq	-	0.1	4.4	μA	PWMPWR=PWMDRV=RSTB=0V
Current consumption	Idd	-	3.2	4.8	mA	VDET=0V,ISET=27kΩ
[PWMPWR Terminal]						
Low input voltage range1	POWL	0	-	0.9	V	
High input voltage range1	POWH	2.1	-	VBAT	V	
Pull down resistor1	POWR	100	300	500	kΩ	PWMPWR=3V
[PWMDRV Terminal]						
Low input voltage range2	PDRVLL	0	-	0.9	V	
High input voltage range2	PDRVH	2.1	-	5.5	V	
Pull down resistor2	DRVRL	100	300	500	kΩ	
[RSTB Terminal]						
Low input voltage range3	RSTBL	0	-	0.9	V	
High input voltage range3	RSTBH	2.1	-	5.5	V	
Pull down resistor3	RSTBR	100	300	500	kΩ	
[FAILFLAG]						
Input resistor	FFIR	1.0	2.0	3.0	kΩ	FAILFLAG=2.5V
Off current	FFIST	-	0.1	2.0	μA	PWMPWR=0V
[Regulator]						
Under voltage lock out	UVLO	2.9	3.3	3.7	V	VBAT falling edge
[Switching Regulator]						
LED control voltage	VLED	0.56	0.70	0.84	V	
Switching frequency	fsw	1.00	1.25	1.50	MHz	RSTB=L (GND short)
Duty cycle limit	Duty	91	95.0	99.0	%	LED1-6=0.3V
SW Nch FET RON	RON	-	0.48	0.58	Ω	ISW=80mA

● Electrical Characteristics - continued

(Unless otherwise specified, VBAT=5V, Ta = +25°C)

Parameter	Symbol	Limits			Unit	Condition
		Min.	Typ.	Max.		
[Protection]						
Over current limit	Ocp	1.4	2.0	2.6	A	OCPSET=68kΩ ^{*1}
OCPSET open protect	OOP	-	0.0	0.1	A	OCPSET=2MΩ
Over voltage limit Input	Ovl	0.96	1.00	1.04	V	Detect voltage of VDET pin
SBD open protect	Sop	0.02	0.05	0.08	V	Detect voltage of VDET pin
VDET leak current	OVIL	-	0.1	1.0	µA	
[Current driver]						
LED maximum current	ILMAX	-	-	30	mA	
LED current accuracy	ILACCU	-	-	±3.0	%	ILED=16mA
LED current matching	ILMAT	-	-	±1.5	%	Each LED current/Average (LED1-6) ILED=16 to 20mA
LED current limiter	ILOCP	-	0	0.1	mA	Current limit value at ISET resistor 1kΩ setting
LED terminal over voltage protect	LEDOVP	10.0	11.5	13.0	V	PWMDRV=2.5V
ISET voltage	Iset	0.5	0.6	0.7	V	

*1 This parameter is tested with DC measurement.

● Pin Descriptions

PIN No.	PIN Name	In/Out	Function	Terminal diagram
1	SW	Out	Switching Tr drive terminal	H
2	SW	Out	Switching Tr drive terminal	H
3	N.C.	-	No connect pin	F
4	PGND	-	PGND for switching Tr	D
5	FAILFLAG	Out	Fail Flag	C
6	OCPSET	In	Current Limiter setting	A
7	VDET	In	Detect input for SBD open and OVP	A
8	TEST	In	TEST signal	J
9	RSTB	In	Reset	J
10	ISET	In	Resister connection for LED current setting	A
11	GND	-	GND for Switching Regulator	B
12	N.C.	-	No connect pin	F
13	LED1	In	Current sink for LED	C
14	LED2	In	Current sink for LED	C
15	LED3	In	Current sink for LED	C
16	LED4	In	Current sink for LED	C
17	LED5	In	Current sink for LED	C
18	LED6	In	Current sink for LED	C
19	N.C.	-	No connect pin	F
20	GND	-	GND for Current driver	B
21	PWMDRV	In	PWM input pin for power ON/OFF only driver	G
22	VBAT	In	Regulator output / Internal power-supply	I
23	PWMPOW	In	PWM input pin for power ON/OFF	E
24	VBAT	In	Switching Tr drive terminal	I
-	Thermal PAD	-	Heat radiation PAD of back side Connect to GND	-

● Pin ESD Type

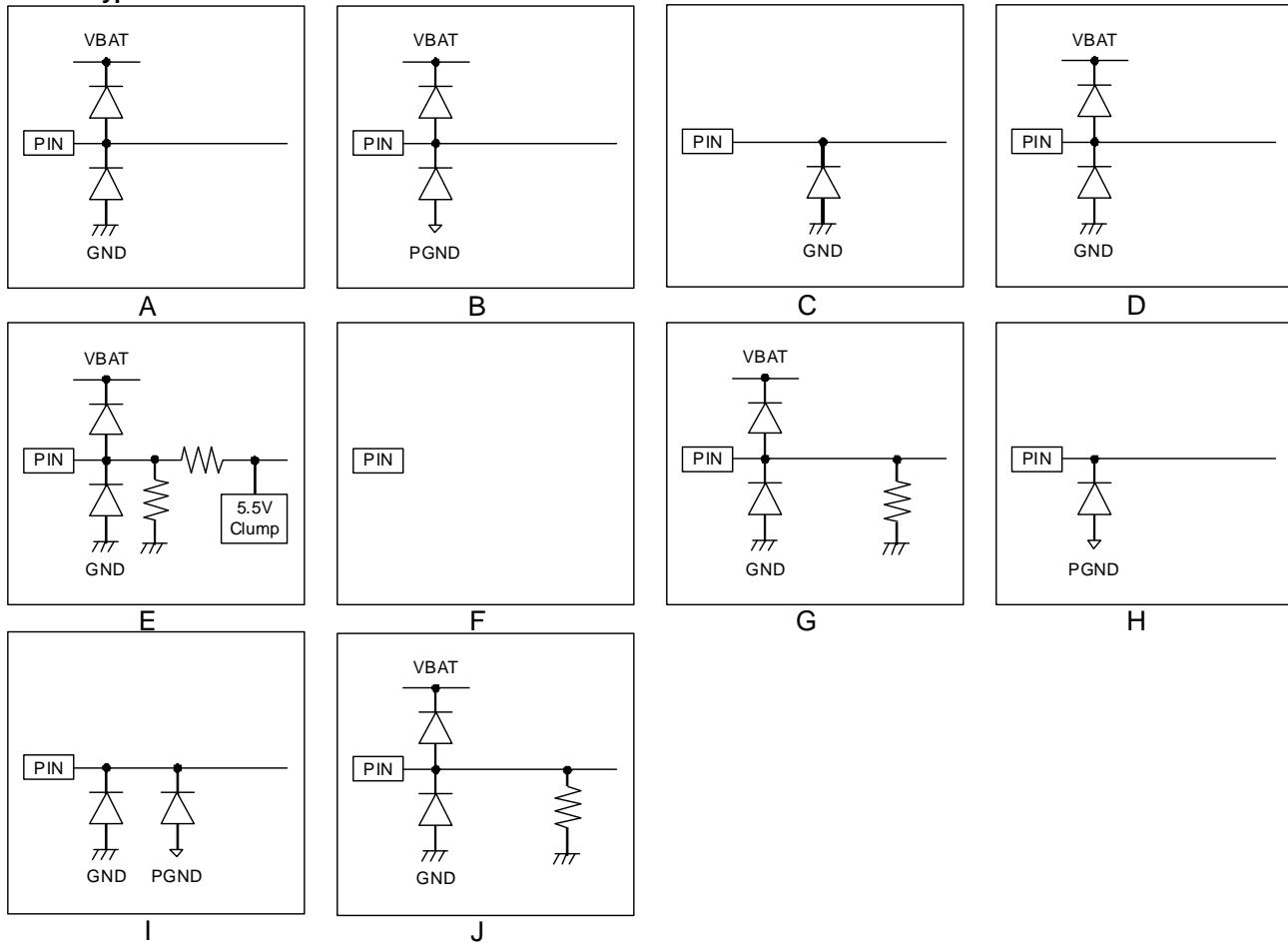
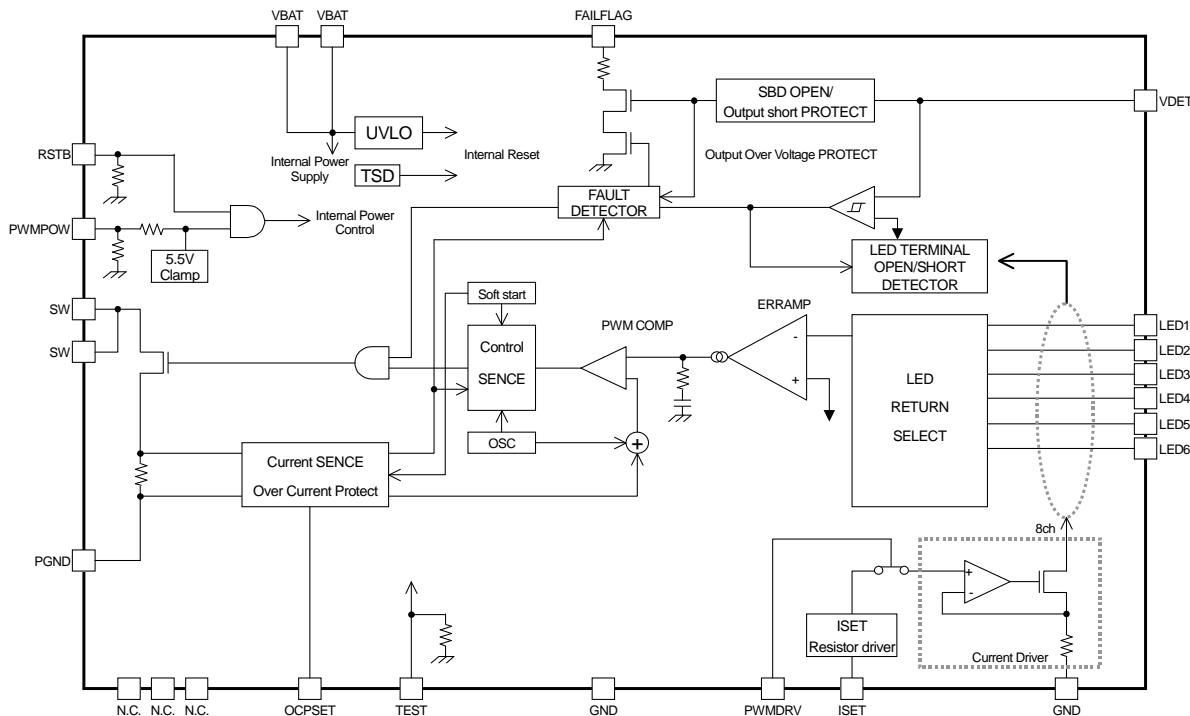


Figure 3. Pin ESD Type

● Block Diagram

Pin number 24pin
Figure 4. BD6590MUV block diagram

● Description of Functions

1) PWM current mode DC/DC converter

While BD6590MUV is power ON, the lowest voltage of LED terms is detected, PWM duty is decided to be 0.7V and output voltage is kept invariably. As for the inputs of the PWM comparator as the feature of the PWM current mode, one is overlapped with error components from the error amplifier, and the other is overlapped with a current sense signal that controls the inductor current into Slope waveform to prevent sub harmonic oscillation. This output controls internal Nch Tr via the RS latch. In the period where internal Nch Tr gate is ON, energy is accumulated in the external inductor, and in the period where internal Nch Tr gate is OFF, energy is transferred to the output capacitor via external SBD. BD6590MUV has many safety functions, and their detection signals stop switching operation at once.

2) Soft start

BD6590MUV has soft start function.

The soft start function prevents large coil current.

Rush current at turning on is prevented by the soft start function.

After PWMPOW, RSTB is changed L→ H, soft start becomes effective for within 4ms and soft start doesn't become effective even if PWMPOW is changed L→H after that.

And, when the H section of PWMPOW is within 4ms, soft start becomes invalid when PWMPOW is input to H more than three times. The invalid of the soft start can be canceled by making PWMPOW, PWMDRV →L.

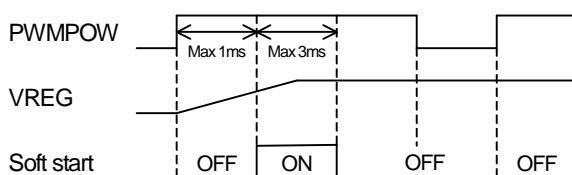


Figure 5. Soft start

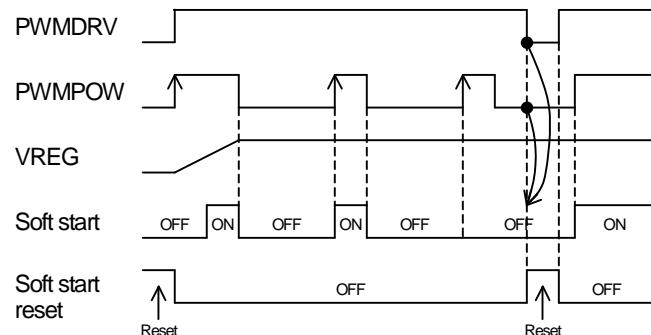


Figure 6. Soft start reset and set

3) FAILFLAG

When the error condition occurs, boost operating is stopped by the protection function, and the error condition is outputted from FAILFLAG. After power ON, when the protection function is operating under about 1ms have passed.

Object of protect function is as shown below.

- Over-voltage protection
- External SBD open detect/ Output Short protection
- LED terminal open/short protection
- Over current limit

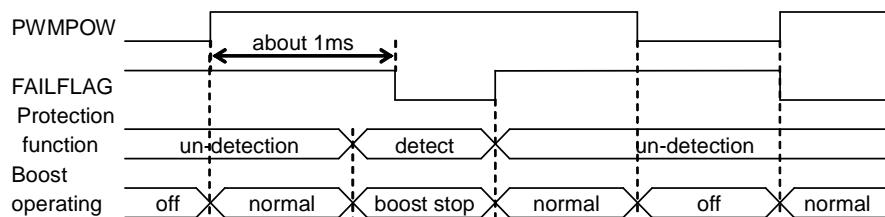


Figure 7. FAILFLAG operating description

● Protection

- Over voltage protection

At such an error of output open as the output DC/DC and the LED is not connected to IC, the DC/DC will boost too much and the VDET terminal exceed the absolute maximum ratings, and may destruct the IC. Therefore, when VDET becomes sensing voltage or higher, the over voltage limit works, and turns off the output Tr, and the pressure up made stop.

At this moment, the IC changes from activation into non-activation, and the output voltage goes down slowly. And, when the Feedback of LED1 isn't returned, so that VOUT will return normal voltage.

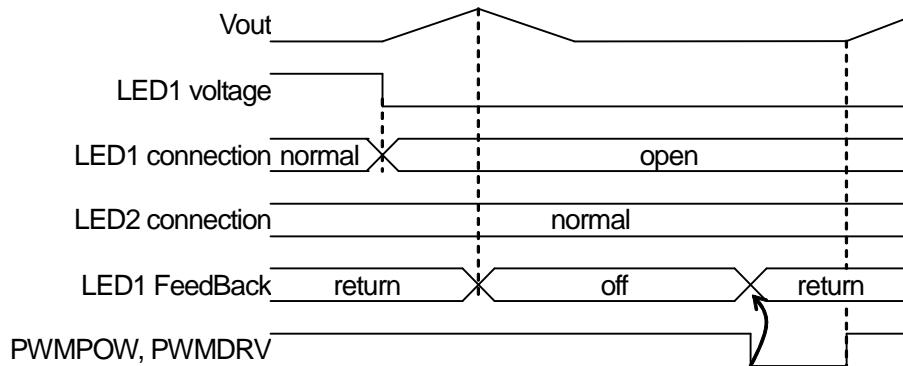


Figure 8. VDET operating description

- External SBD open detect / Output short protection

In the case of external SBD is not connected to IC, or VOUT is shorted to GND, the coil or internal Tr may be destructed. Therefore, at such an error as VDET becoming 0.05V or below, and turns off the output Tr, and prevents the coil and the IC from being destructed. And the IC changes from activation into non-activation, and current does not flow to the coil (0mA).

- Thermal shut down

BD6590MUV has thermal shut down function.

The thermal shut down works at 175°C or higher, and the IC changes from activation into non-activation.

● How to Set Over Voltage Limit

This section is especially mentioned here because the spec shown electrical characteristic is necessary to explain this section.

Over voltage limit	min 0.96V	typ 1.00V	max 1.04V
LED control voltage	min 0.56V	typ 0.70V	max 0.84V
LED terminal over voltage protect	min 10.0V	typ 11.5 V	max 13.0V

1. Calculate the conditions that the total value of LED VF is MAX.

Example) In the case of serial 8 LEDs with VF=2.9V(min), 3.2V(typ), 3.5V(max) => $3.5V \times 8 = 28V$

2. Then calculate the biggest value of output with the following formula.

The biggest value of output = the biggest value calculated for 1 + the biggest value of LED terminal voltage. (0.84V)

Example) The biggest value of output = $28V + 0.84V = 28.84V$

3. Set the smallest value of over voltage larger than the biggest value of output.

If over voltage is closer to the total value of VF, it could be occurred to detect over voltage by ripple, noise, and so on.

It is recommended that some margins should be left on the difference between over voltage and the total value of VF.

This time around 6% margin is placed.

Example) Against the biggest value of output = 28.84V, the smallest value of over voltage = $28.84V \times 1.06 = 30.57V$

I_c over voltage limit min=0.96V, typ=1.00V, max=1.04V

typ = $30.57V \times (1.00V / 0.96V) = 31.8V$

max = $31.8V \times (1.04V / 1.00V) = 33.1V$

4. The below shows how to control resistor setting over voltage

Please fix resistor high between VDET and output and then set over voltage after changing resistor between VDET and GND. While PWM is off, output voltage decreases by minimizing this resistor. Due to the decrease of output voltage, ripple of output voltage increases, and singing of output condenser also becomes bigger.

Example) Selecting OVP resistor.

(Example 1) VF=3.6V max, serial = 7 LED

OVP = 1.0V, R₁ = 2.2MΩ, R₂ = 78.7kΩ

V_{OUT} = $1.0 \times (2.2M\Omega + 78.7k\Omega) / 78.7k\Omega = 28.95V$

(Example 2) VF=3.6V max, serial = 8 LED

OVP = 1.0V, R₁ = 2.2MΩ, R₂ = 69.8kΩ

V_{OUT} = $1.0 \times (2.2M\Omega + 69.8k\Omega) / 69.8k\Omega = 32.52V$

(Example 3) VF=3.6V max, serial = 9 LED

OVP = 1.0V, R₁ = 2.2MΩ, R₂ = 62kΩ

V_{OUT} = $1.0 \times (2.2M\Omega + 62k\Omega) / 62k\Omega = 36.48V$

(Example 4) VF=3.6V max, serial = 10 LED

OVP = 1.0V, R₁ = 1.0MΩ, R₂ = 26.7kΩ

V_{OUT} = $1.0 \times (1.0M\Omega + 26.7k\Omega) / 26.7k\Omega = 38.45V$

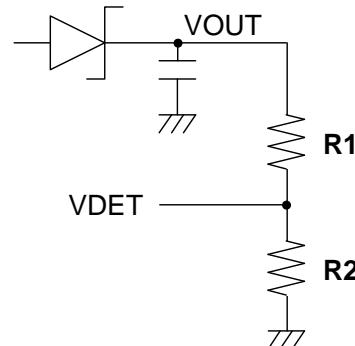


Figure 9. Control resistor setting

- Over Current Limit

Over current flows the current detection resistor that is connected to internal switching transistor source and between PGND, Current sense voltage turns more than detection voltage decided with OCPSET, over current protection is operating and it is prevented from flowing more than detection current by reducing ON duty of switching Tr without stopping boost. As over current detector of BD6590MUV is detected peak current, current more than over current setting value does not flow. And, over current value can decide freely by changing OCPSET voltage.

The range of over current setting is from 0.5A to 2.5A.

<Derivation sequence of detection resistor>

$$R(\text{OCPSET}) = 34\text{k}\Omega \times \text{Over current setting}$$

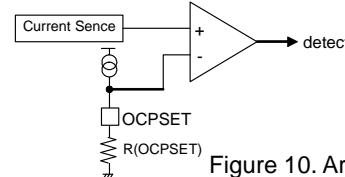


Figure 10. Architecture

TYP value of over current is 2A, MIN = 1.4A and MAX = 2.6A and after the current value which was necessary for the normal operation was decided, detection resistor is derived by using MIN value of over current detection value.

For example, detection resistor when typ value was set at 2A is given as shown below.

$$\text{Detection resistor} = 34\text{k}\Omega \times 2\text{A} = 68\text{k}\Omega$$

MAX current dispersion of this detection resistor value is

$$\text{MAX current} = 2\text{A} \times 1.3 = 2.6\text{A}$$

For example, $34\text{k}\Omega \rightarrow 1\text{A}$, $68\text{k}\Omega \rightarrow 2\text{A}$

<The estimate of the current value which need for the normal operation >

As over current detector of BD6590MUV is detected the peak current, it have to estimate peak current to flow to the coil by operating condition.

In case of,

- Supply voltage of coil = VIN
- Inductance value of coil = L
- Switching frequency = fsw
- Output voltage = VOUT
- Total LED current = IOUT
- Average current of coil = lave
- Peak current of coil = Ipeak
- Efficiency = eff
- ON time of switching transistor = Ton

$$I_{\text{peak}} = (\text{VIN} / L) \times (1 / \text{fsw}) \times (1 - (\text{VIN} / \text{VOUT}))$$

$$I_{\text{ave}} = (\text{VOUT} \times \text{IOUT} / \text{VIN}) / \text{eff}$$

$$T_{\text{on}} = (I_{\text{ave}} \times (1 - \text{VIN} / \text{VOUT}) \times (1 / \text{fsw}) \times (L / \text{VIN}) \times 2)^{1/2}$$

Each current is calculated.

As peak current varies according to whether there is the direct current superposed, the next is decided.

$$(1 - \text{VIN} / \text{VOUT}) \times (1 / \text{fsw}) < T_{\text{on}} \rightarrow \text{peak current} = I_{\text{peak}} / 2 + I_{\text{ave}}$$

$$(1 - \text{VIN} / \text{VOUT}) \times (1 / \text{fsw}) > T_{\text{on}} \rightarrow \text{peak current} = (V_{\text{IN}} / L) \times T_{\text{on}}$$

(Example 1)

In case of, VIN=6.0V, L=4.7μH, fsw=1.25MHz, VOUT=39V, IOUT=80mA, Efficiency=85%

$$I_{\text{peak}} = (6.0V / 4.7\mu H) \times (1 / 1.25\text{MHz}) \times (1 - (6.0V / 39V)) = 0.86A$$

$$I_{\text{ave}} = (39V \times 80mA / 6.0V) / 85\% = 0.61A$$

$$T_{\text{on}} = (0.61A \times (1 - 6.0V / 39V) \times (1 / 1.25\text{MHz}) \times (4.7\mu H / 6.0V) \times 2)^{1/2} = 0.81\mu s$$

$$(1 - \text{VIN} / \text{VOUT}) \times (1 / \text{fsw}) = 0.68\mu s < T_{\text{on}}$$

$$\text{Peak current} = 0.68A / 2 + 0.61A = 1.04A$$

(Example 2)

In case of, VIN=12.0V, L=4.7μH, fsw=1.25MHz, VOUT=39V, IOUT=80mA, Efficiency=85%

$$I_{\text{peak}} = (12.0V / 4.7\mu H) \times (1 / 1.25\text{MHz}) \times (1 - (12V / 39V)) = 1.41A$$

$$I_{\text{ave}} = (39V \times 80mA / 12.0V) / 85\% = 0.31A$$

$$T_{\text{on}} = (0.31A \times (1 - 12V / 39V) \times (1 / 1.25\text{MHz}) \times (4.7\mu H / 12V) \times 2)^{1/2} = 0.36\mu s$$

$$(1 - \text{VIN} / \text{VOUT}) \times (1 / \text{fsw}) = 0.55\mu s > T_{\text{on}}$$

$$\text{Peak current} = 12V / 4.7\mu H \times 0.36\mu s = 0.92A$$

*When too large current is set, output overshoot is caused, be careful enough because it is led to break down of the IC in case of the worst.

- Soft start of over current limit for application

When the capacitor of OCPSET is set as figure, over current limit can become setting value slowly.

This effect is same as internal soft start.

When you want to reduce peak current than internal soft start on startup, this way is effective.

But, this action repeat when the timing that PWMPOW change L to H, so to do PWM control with PWMPOW terminal, rise time of over current limit must be set into Hi time of PWM control, and please don't connect the capacitor.

Show example of rising wave form with OCPSET 330pF.

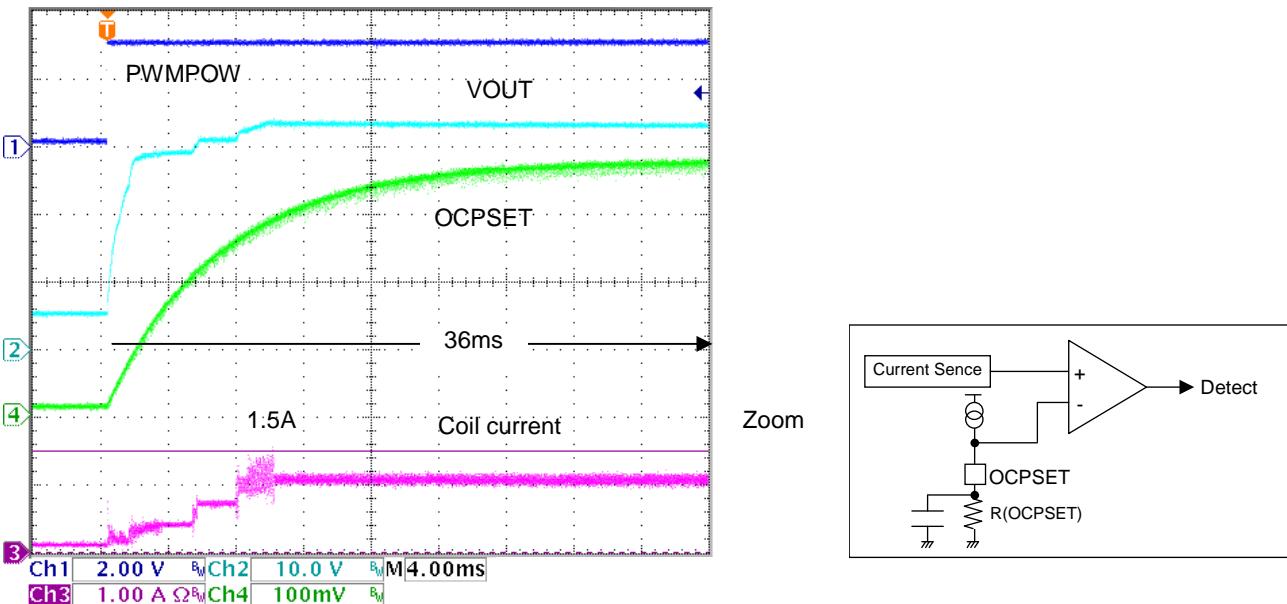


Figure 11. VBAT=5V, 6parallel 10serial 20mA/ch, OCPSET=68kΩ,330nF

● Operating of the Application Deficiency

1) When 1 LED or 1string OPEN during the operating

The LED string that became OPEN isn't lighting, but other LED strings are lighting.

Then LED terminal is 0VOUTput boosts up to the over voltage protection voltage. When over voltage is detected, the feedback of open string isn't returned, so that VOUT will return normal voltage.

In the case that the voltage of 2 LED terminals becomes more than 25V(Absolute maximum ratings) as VOUT boosts up to the over voltage protection voltage, please pay attention carefully that 2 LED terminals could be broken up in setting over voltage protection.

OVP setting when selecting terminals

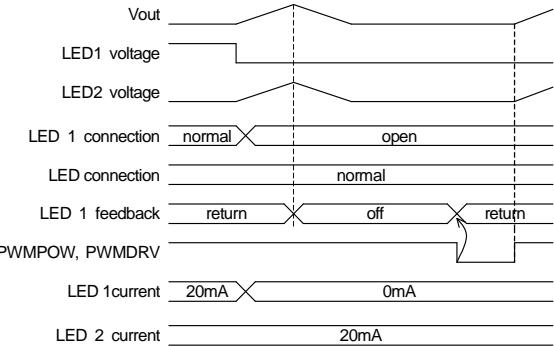
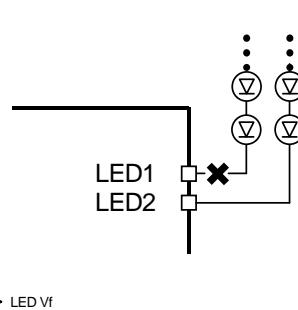
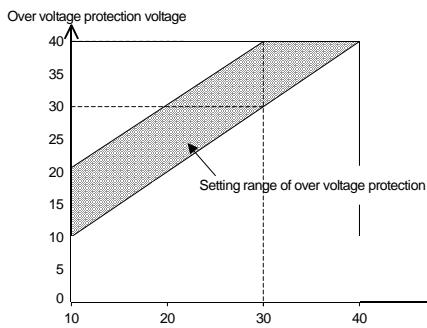


Figure 12. LED OPEN detect

Moreover, excessively high level of over voltage limit in terminal setting makes it happen that LED terminal voltage exceeds LED terminal over voltage protect, which accordingly turn off LED lights. In order to prevent this problem, please see "How to set the external resistor of over voltage limit (p.7)" and then set over voltage referring to application.

2) When LED short-circuited in the plural

All LED strings is turned on unless LED1 to 6 terminal voltage is more than 11.5V.

When it was more than 11.5V only the strings which short-circuited is turned off normally and LED current of other lines continue to turn on.

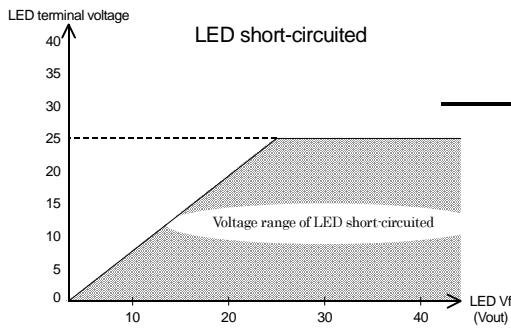
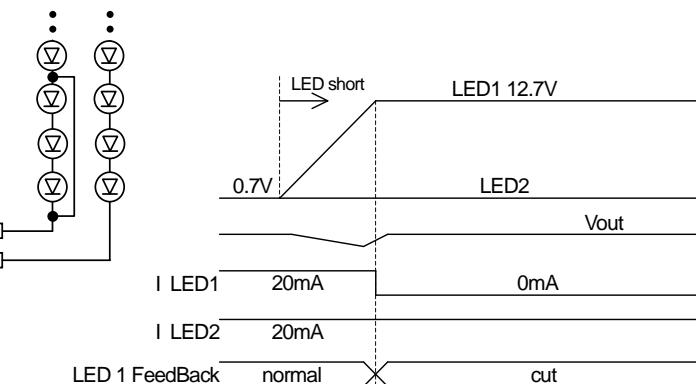


Figure 13. LED short detect



3) When Schottky diode comes off

IC and a switching transistor aren't destroyed because boost operating stops by the Schottky diode coming off protected function.

4) When the resistor of over current detection comes off

All the LEDs do not turn on due to open protect of the OCP resistor, which stops boost operation and consequently prevents passing LED current.

● Control Signal Input Timing

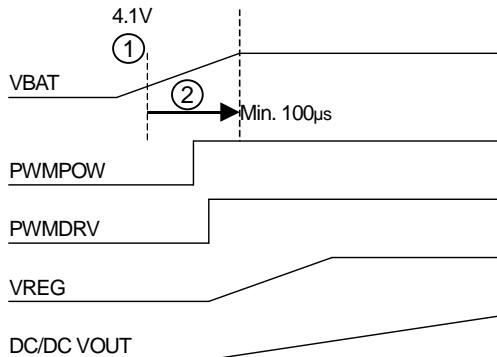
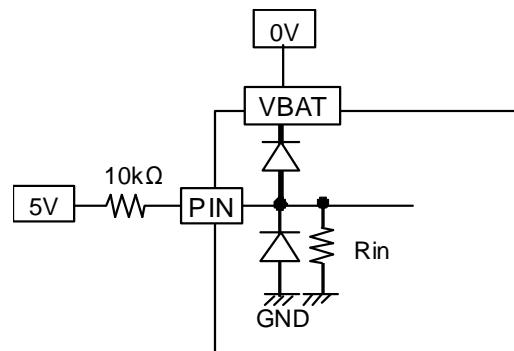


Figure 14. Control signal timing

Figure 15. Voltage with a control sign higher than VBAT
Example corresponding to application of conditions

In case you input control signs, such as PWMPOW, and PWMDRV, in the condition that the standup of supply voltage (VBAT) is not completed, be careful of the following point.

① Input each control signal after VBAT exceeds 4.1V.

② When you input PWMPOW during the standup of VBAT, please give the standup time as Min.100μs from 4.1V to stable voltage for VBAT.

There is no timing limitation at each input signal of PWMPOW and PWMDRV.

If each control sign changes into a condition higher than VBAT in (1) and (2), it goes via the ESD custody diode by the side of VBAT of each terminal. A power supply is supplied to VBAT and there is a possibility of malfunctioning. In order to avoid this condition, as shown in the above figure, please insert about 10kΩ in a signal line, and apply current qualification. Please confirm an internal pull down resistor in the block diagram (P.4) and electrical property(P.2).

● Start Control (PWMPOW) and Select LED Current Driver (PWMDRV)

BD6590MUV can control the IC system by PWMPOW, and IC can power off compulsory by setting 0.9V or below. Also, It powers on PWMPOW is at more than 2.1V.

After it's selected to PWMPOW=H, When it is selected at PWMDRV=H, LED current decided with ISET resistance flow. Next, When it is selected at PWMDRV=L, LED current stop to flow.

RSTB	PWMPOW	PWMDRV	IC	LED current
L	H, L	H, L	Off	OFF
H	L	L	Off	OFF
H	H	L	On	OFF
H	L	H	Off	OFF
H	H	H	On	Current decided with ISET

● How to Select the Number of LED Lines of the Current Driver

When the number of LED lines of the current driver is reduced, the un-select can be available by setting the unnecessary LED1 to 6 terminals OPEN. In the case of using 4 lines and so on, please connect the unnecessary 2 lines OPEN.

Then please set RSTB, PWMPOW and PWMDRV "H" and finish selecting the lines within the process of softstart. If the level of over voltage limit is set too high, the connected LED lines exceed LED terminal over voltage protect and are judged as unnecessary lines.

Please make it sure referring "How to set over voltage limit (p.7)".

Additionally, once the terminals are judged as unnecessary, this information never can be reset without setting RSTB, PWMPOW and PWMDRV "L".

● LED Current Setting Range

LED current can set up Normal current by resistance value (RISET) connecting to ISET voltage.

Setting of each LED current is given as shown below.

$$\text{Normal current} = 432/\text{RISET (A)}$$

Also, Normal current setting range is 10mA to 30mA. LED current becomes a leak current MAX 2 μ A at OFF setting. When using beyond current setting range, please be careful that the error in LED current setting could be large.

ISET Normal current setting example

RISET	LED current
18k Ω (E24)	24.0mA
22k Ω (E24)	19.6mA
24k Ω (E24)	18.0mA
27k Ω (E24)	16.0mA
30k Ω (E24)	14.4mA
33k Ω (E24)	13.1mA

● Brightness Control

There are two dimming method is available, first method is analog dimming that apply analog voltage to ISET terminal, and second method is PWM control via digital dimming of PWMDRV or PWMPOW. Because each method has the different merit, please choose a suitable method for the application of use.

Two techniques can be used as digital dimming by the PWM control One is PWM control of current driver, the other is PWM control of power control.

As these two characteristics are shown in the below, selects to PWM control process comply with application.

- Efficiency emphasis in the low brightness which has an influence with the battery life → 2) Power control PWM control
- LED current dispersion emphasis in the PWM brightness control → 1) Current driver PWM control

(Reference)

PWM regulation process	Efficiency of LED current 0.5mA (PWM Duty=2.5%)	PWM frequency 200Hz Limit dispersion capability of low duty
Current driver	74.8%	0.04%
Power control	91%	0.40%

1) Current driver PWM control is controlled by providing PWM signal to PWMDRV, as it is shown Figure 16.

The current set up with ISET is chosen as the H section of PWMDRV and the current is off as the L section. Therefore, the average LED current is increasing in proportion to duty cycle of PWMDRV signal. This method that it lets internal circuit and DC/DC to work, because it becomes to switch the driver, the current tolerance is a few when the PWM brightness is adjusted, so it makes it possible to brightness control until 5 μ s (MIN0.1% at 200Hz). And, don't use for the brightness control, because effect of ISET changeover is big under 1 μ s ON time and under 1 μ s OFF time. Typical PWM frequency is 100Hz to 25kHz.

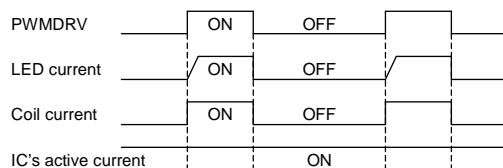


Figure 16. PWMDRV sequence

2) Power control PWM control is controlled by providing PWM signal to PWMPOW, as it is shown Figure 17. The current setting set up with PWMDRV logic is chosen as the H section and the current is off as the L section. Therefore, the average LED current is increasing in proportion to duty cycle of PWMPOW signal. This method is, because IC can be power-off at off-time, the consumption current can be suppress, and the high efficiency can be available, so it makes it possible to brightness control until 50 μ s (MIN1% at 200Hz). And, don't use for the brightness control, because effect of power ON/OFF time changeover is big under 50 μ s ON time and under 50 μ s OFF time.

Typical PWM frequency is 100Hz to 1kHz.

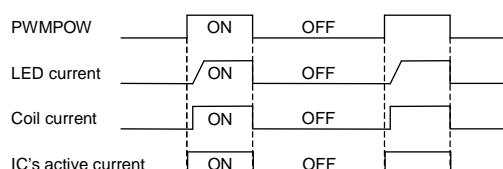
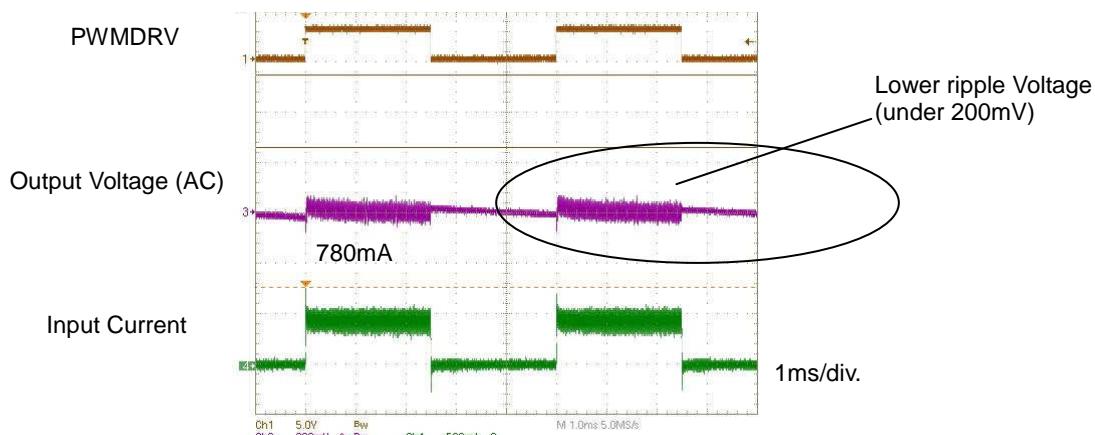


Figure 17. PWMPOW sequence

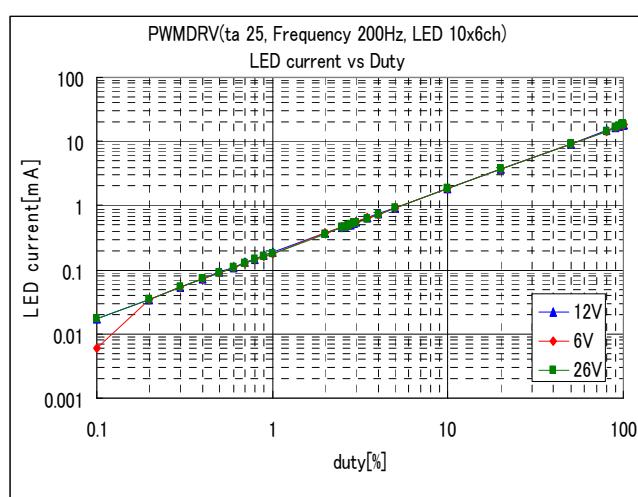
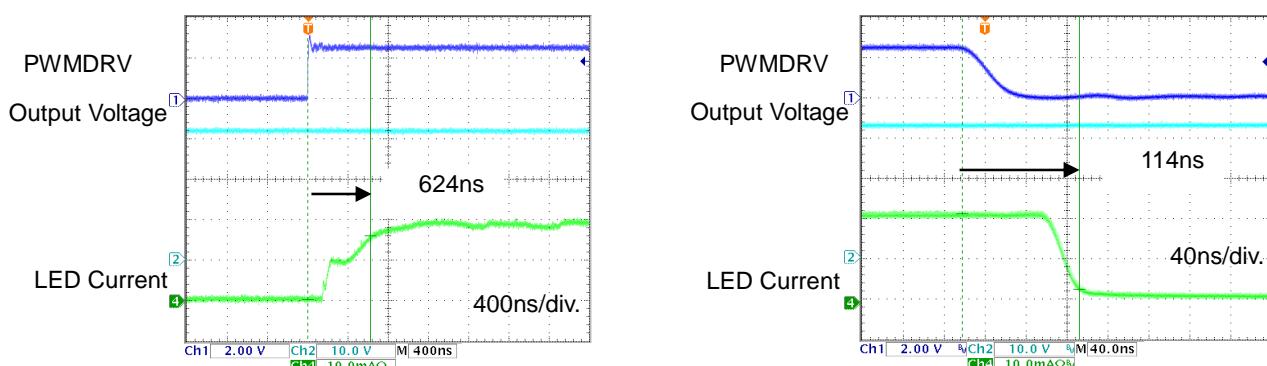
● Output Voltage Ripple for PWM Dimming

Conditions: 8serial 6parallel, LED current=20mA/ch, VBAT=5V, Coil Power=7V, Ta=25°C, output capacitor =2.2μF(50V/B3)

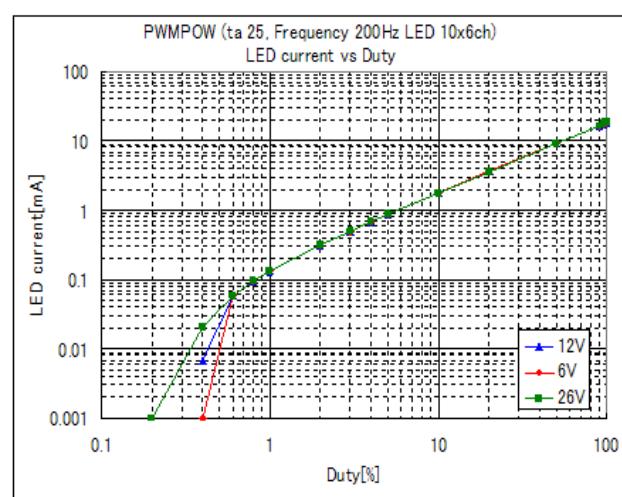


● LED Current Rise and Fall for PWM Dimming

Conditions: 8serial 6parallel, LED current=20mA/ch, VBAT=5V, Coil Power=7V, Ta=25°C, output capacitor=2.2μF(50V/B3)



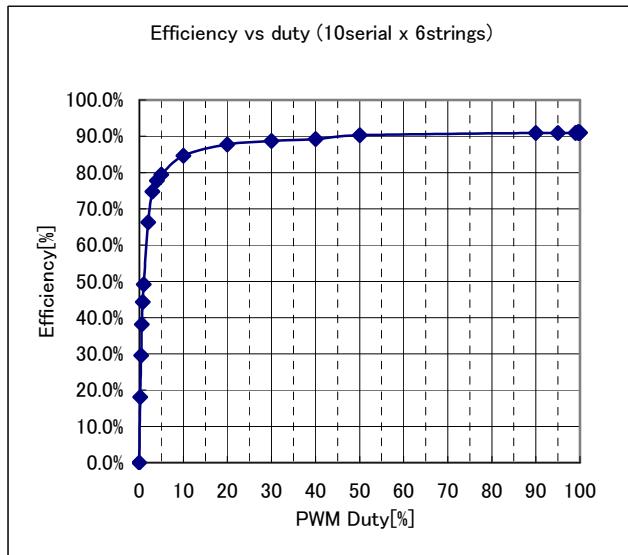
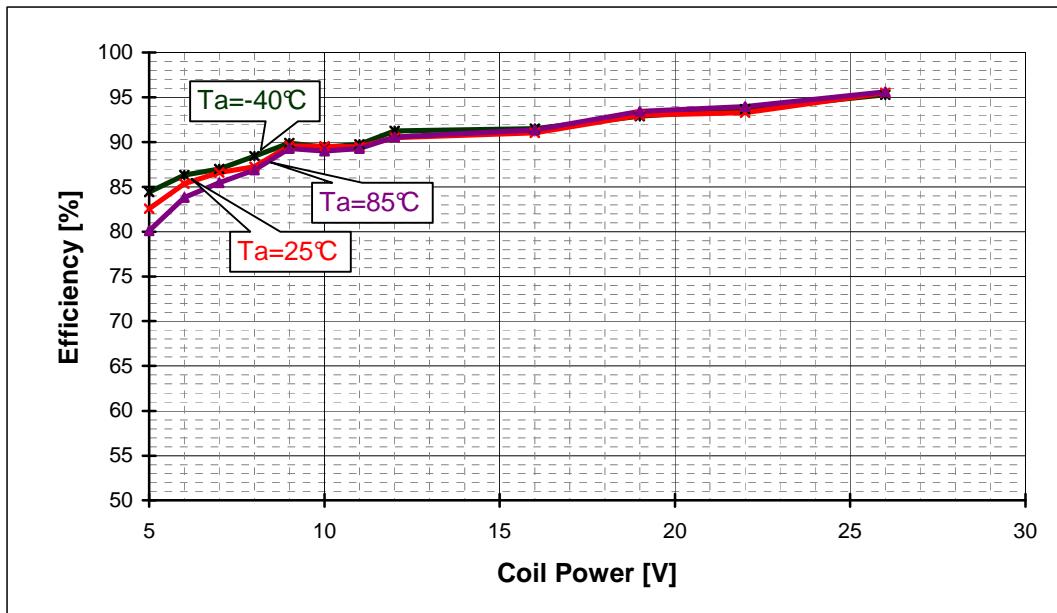
PWM characteristics of current driver PWM



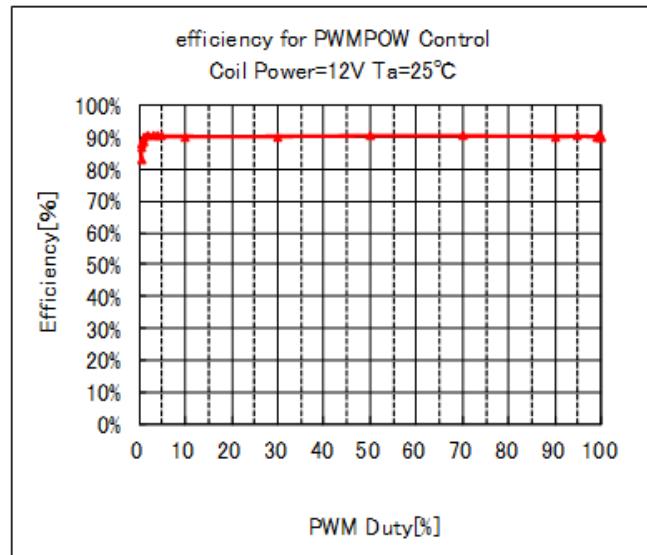
PWM characteristics of power control PWM

● Main Characteristics of Efficiency

Conditions: 10serial 6parallel, LED current=20mA/ch, output capacitor=2.2μF(50V/B3)



Efficiency of current driver PWM



Efficiency of power control PWM

● The Coil Selection

The DC/DC is designed by more than $4.7\mu\text{H}$. When L value sets to a lower value, it is possibility that the specific sub-harmonic oscillation of current mode DC / DC will be happened. Please do not let L value to $3.3\mu\text{H}$ or below.

And, L value increases, the phase margin of DC / DC becomes to zero. Please enlarge the output capacitor value when you increase L value.

Example)

4.7 μ H	=	output capacitor	2.2 μ F/50V	1pcs
6.8 μ H	=	output capacitor	2.2 μ F/50V	2pcs
10 μ H	=	output capacitor	2.2 μ F/50V	3pcs

This value is just examples, please made sure the final judgment is under an enough evaluation.

● The Separation of the IC Power Supply and Coil Power Supply

BD6590MUV can work in separating the power source in both IC power supply and coil power supply. With this application, it can obtain that decrease of IC power consumption, and the applied voltage exceeds IC rating 7V.

That application is shown in below Figure 18. The higher voltage source is applied to the power source of coil that is connected from 4.5V to 5.5V into IC VBAT, please follow the recommend design in Figure 18. It connects VBAT terminal and VREG terminal together at IC outside.

When the coil power supply is applied, it is no any problem even though IC power supply is the state of 0V. Although IC power supply is set to 0V, pull-down resistance is arranged for the power off which cuts off the leak route from coil power supply in IC inside, the leak route is cut off. And, there is no power on-off sequence of coil power supply and IC power supply.

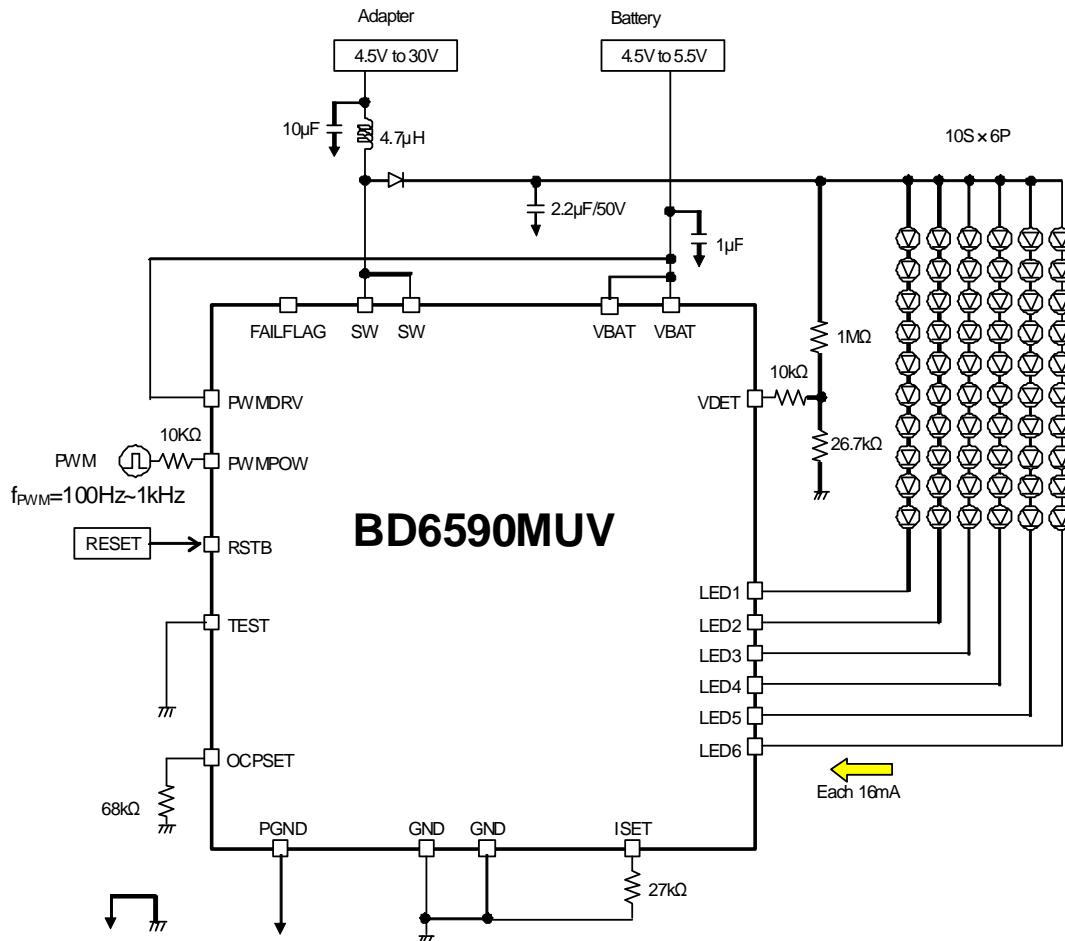


Figure 18. Application at the time of power supply isolation (6parallel)

● PCB Layout

In order to make the most of the performance of BD6590MUV, its PCB layout is very important. Characteristics such as efficiency and ripple and the likes change greatly with layout patterns, which please note carefully.

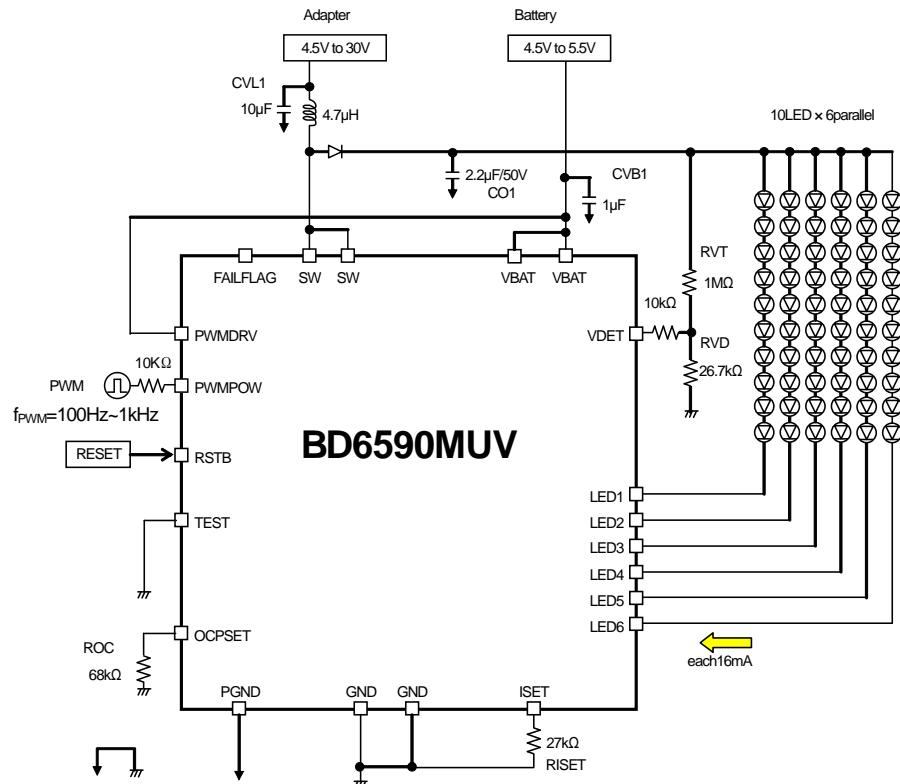


Figure 19. Layout

<Input capacitor CVL1 (10 μ F) for coil>

Connect input capacitor CVL1 (10 μ F) as close as possible between coil L1 and PGND.

<Input bypass capacitor CVB1 (1 μ F) for IC>

Put input bypass capacitor CVB1 (1 μ F) as close as possible between VBAT and PGND pin.

<Schottky barrier diode SBD>

Connect schottky barrier diode SBD as close as possible between coil1 and SW pin.

<Output capacitor CO1>

Connect output capacitor CO1 between cathode of SBD and PGND.

Make both PGND sides of CVL1 and CO1 as close as possible.

<LED current setting resistor RISET(27k Ω)>

Connect LED current setting resistor RISET(27k Ω) as close as possible between ISET pin and GND.

There is possibility to oscillate when capacity is added to ISET terminal, so pay attention that capacity isn't added.

<Over current limit setting resistor ROC(68k Ω)>

Connect Over current limit setting resistor ROC(68k Ω) as close as possible between OCPSET pin and GND.

<Over current limit setting resistor RVT(1M Ω) & RVD(26.7k Ω)>

Put over current limit setting resistor RVT(1M Ω) & RVD(26.7k Ω) as close as possible VDET pin so as not to make the wire longer, which possibly causes the noise and also detects over voltage protection by mistake.

<Connect to GND and PGND>

GND is analog ground, and PGND is power ground. PGND might cause a lot of noise due to the coil current of PGND.

Try to connect with analog ground, after smoothing with input capacitor CVL1 and output capacitor CO1.

<Heat radiation of back side PAD>

PAD is used for improving the efficiency of IC heat radiation. Solder PAD to GND pin (analog ground).

Moreover, connect ground plane of board using via as shown in the patterns of next page.

The efficiency of heat radiation improves according to the area of ground plane.

<Others>

When those pins are not connected directly near the chip, influence is given to the performance of BD6150, and may limit the current drive performance. As for the wire to the inductor, make its resistance component small so as to reduce electric power consumption and increase the entire efficiency.

The layout pattern in consideration of these is shown in the next page.

● Recommended PCB Layout

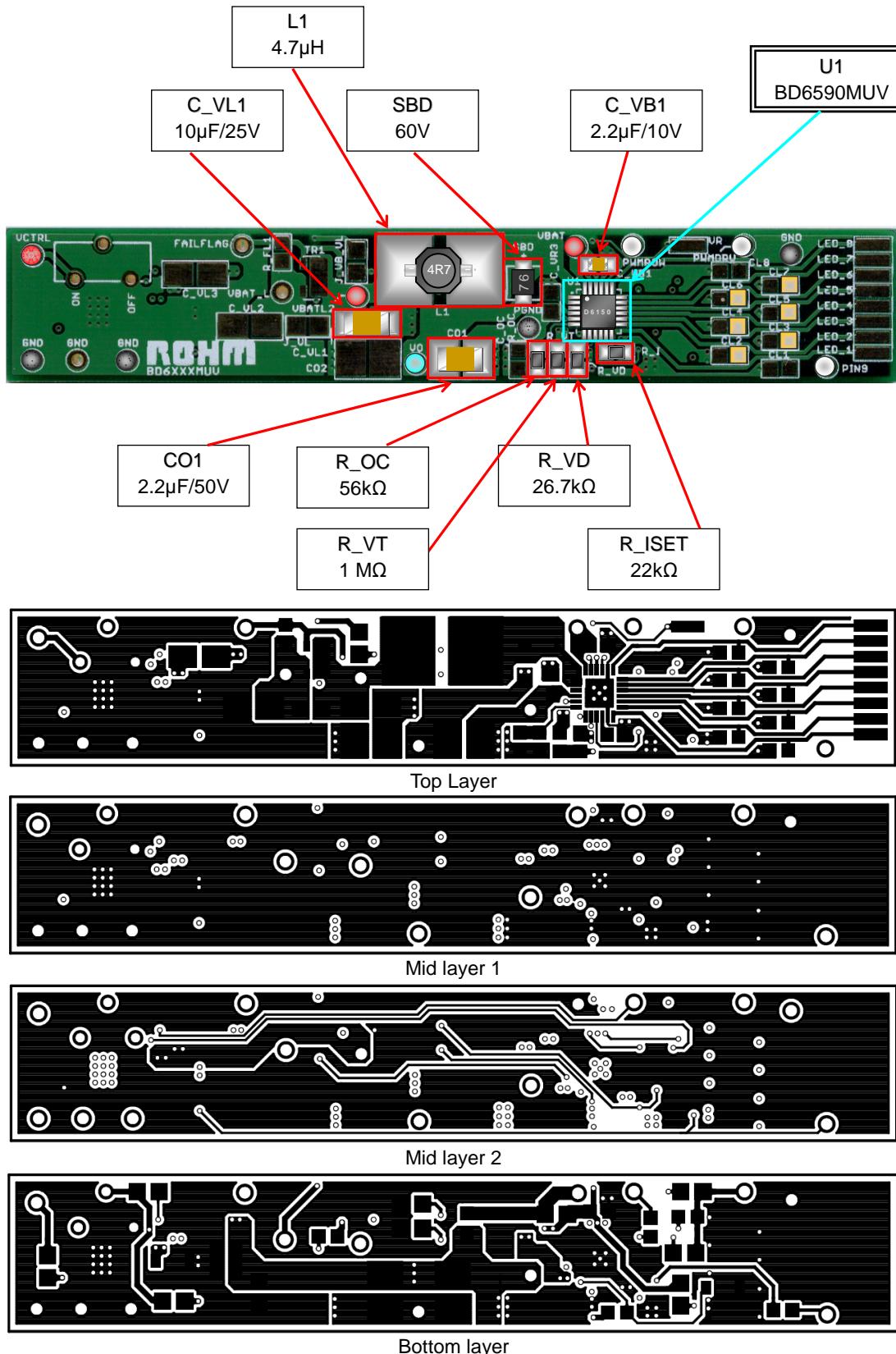


Figure 20. PCB Layout

● Selection of External Parts

Recommended external parts are as shown below.

When to use other parts than these, select the following equivalent parts.

•Coil

Value	Manufacturer	Product number	Size			DC current (mA)	DCR (Ω)
			Vertical	Horizontal	Height		
4.7μH	TDK	LTF5022T-4R7N2R0-LC	5.0	5.2	2.2	2000	0.073
4.7μH	TDK	VLP6810T-4R7M1R6	6.3	6.8	1.0	1600	0.167
10μH	TDK	VLP6810T-100M1R1	6.3	6.8	1.0	1100	0.350
4.7μH	TOKO	A915AY-4R7M	5.2	5.2	3.0	1870	0.045
4.7μH	TOKO	B1015AS-4R7M	8.4	8.3	4.0	3300	0.038

•Capacitor

Value	Pressure	Manufacturer	Product number	Size			TC	Capa Tolerance
				Vertical	Horizontal	Height		
[Supply voltage capacitor]								
2.2μF	10V	MURATA	GRM188B31A225K	1.6	0.8	0.8±0.1	B	+/-10%
4.7μF	25V	MURATA	GRM319R61E475K	3.2	1.6	0.85±0.1	X5R	+/-10%
4.7μF	25V	MURATA	GRM21BR61E475K	2.0	1.25	1.25±0.1	X5R	+/-10%
10μF	25V	MURATA	GRM31CB31E106K	3.2	1.6	1.6±0.2	B	+/-10%
10μF	10V	MURATA	GRM219R61A106K	2.0	1.25	0.85±0.15	X5R	+/-10%
[Output capacitor]								
1μF	50V	MURATA	GRM31MB31H105K	3.2	1.6	1.15±0.1	B	+/-10%
1μF	50V	MURATA	GRM21BB31H105K	2.0	1.25	1.25±0.1	B	+/-10%
2.2μF	50V	TDK	C3225JB1H225K	3.2	2.5	2.0±0.2	B	+/-10%
2.2μF	50V	MURATA	GRM31CB31H225K	3.2	1.6	1.6±0.2	B	+/-10%
0.33μF	50V	MURATA	GRM219B31H334K	2.0	1.25	0.85±0.1	B	+/-10%

•Resistor

Value	Tolerance	Manufacturer	Product number	Size		
				Vertical	Horizontal	Height
10kΩ	±0.5%	ROHM	MCR03PZPZD1002	1.6	0.8	0.45
15kΩ	±0.5%	ROHM	MCR03PZPZD1502	1.6	0.8	0.45
18kΩ	±0.5%	ROHM	MCR03PZPZD1802	1.6	0.8	0.45
22kΩ	±0.5%	ROHM	MCR03PZPZD2202	1.6	0.8	0.45
24kΩ	±0.5%	ROHM	MCR03PZPZD2402	1.6	0.8	0.45
27kΩ	±0.5%	ROHM	MCR03PZPZD2702	1.6	0.8	0.45
30kΩ	±0.5%	ROHM	MCR03PZPZD3002	1.6	0.8	0.45
33kΩ	±0.5%	ROHM	MCR03PZPZD3302	1.6	0.8	0.45
56kΩ	±0.5%	ROHM	MCR03PZPZD5602	1.6	0.8	0.45
62kΩ	±0.5%	ROHM	MCR03PZPZD6202	1.6	0.8	0.45
68kΩ	±0.5%	ROHM	MCR03PZPZD6802	1.6	0.8	0.45
75kΩ	±0.5%	ROHM	MCR03PZPZD7502	1.6	0.8	0.45
2.2MΩ	±0.5%	ROHM	MCR03PZPZD2204	1.6	0.8	0.45

•SBD

Pressure	Manufacturer	Product number	Size		
			Vertical	Horizontal	Height
60V	ROHM	RB160M-60	3.5	1.6	0.8

The coil is the part that is most influential to efficiency. Select the coil whose direct current resistor (DCR) and current - inductance characteristic is excellent. BD6xxx is designed for the inductance value of 4.7μH. Don't use the inductance value. less than 3.3μH. Select a capacitor of ceramic type with excellent frequency and temperature characteristics. Further, select Capacitor to be used with small direct current resistance.

● About Heat Loss

In heat design, operate the DC/DC converter in the following condition.
(The following temperature is a guarantee temperature, so consider the margin.)

1. Ambient temperature Ta must be less than 85°C.
2. The loss of IC must be less than dissipation Pd.

● Application Example

- LED current setting controlled ISETH resistor.
 - 14.7kΩ : 29.59mA
 - 21.5kΩ : 20.1mA
 - 27.0kΩ : 16.0mA
- Brightness control
 - Please input PWM pulse from PWMPOW or PWMDRV terminal.
 - Please refer to function

15inch panel

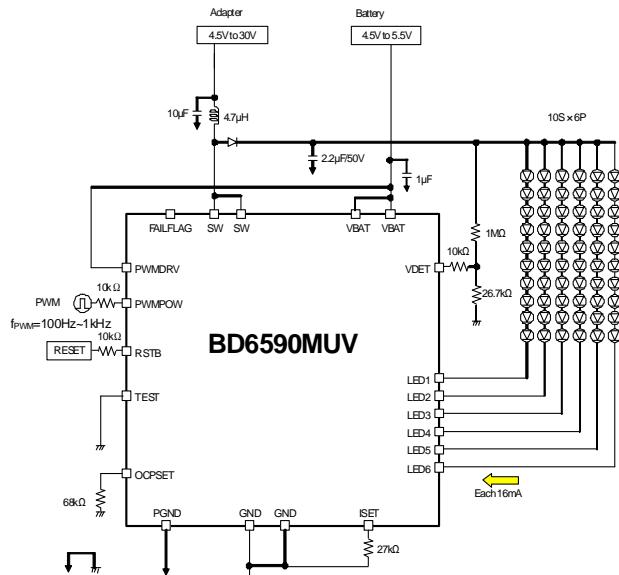


Figure 21. 10series × 6Parallel, LED current 16mA,
Switching frequency 1250kHz setting example
Power control PWM application

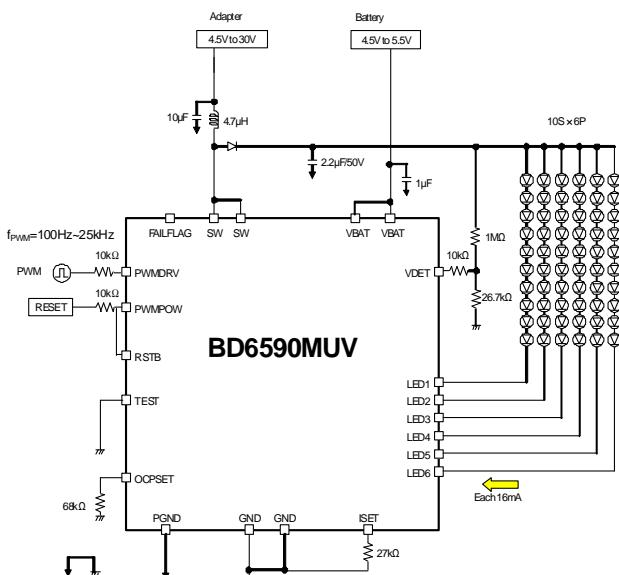


Figure 22. 10series × 6parallel, LED current16mA,
Switching frequency 1250kHz setting example
Current driver PWM application

13 to 14inch panel

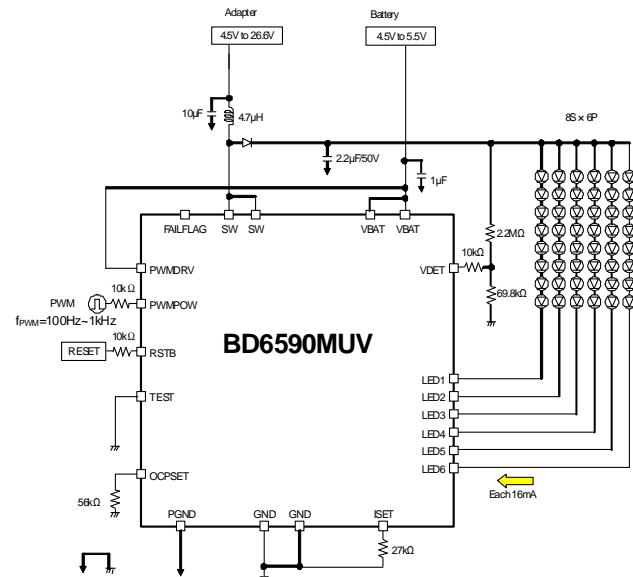


Figure 23. 8series × 6parallel, LED current 16mA,
Switching frequency 1250kHz setting example
Power control PWM application

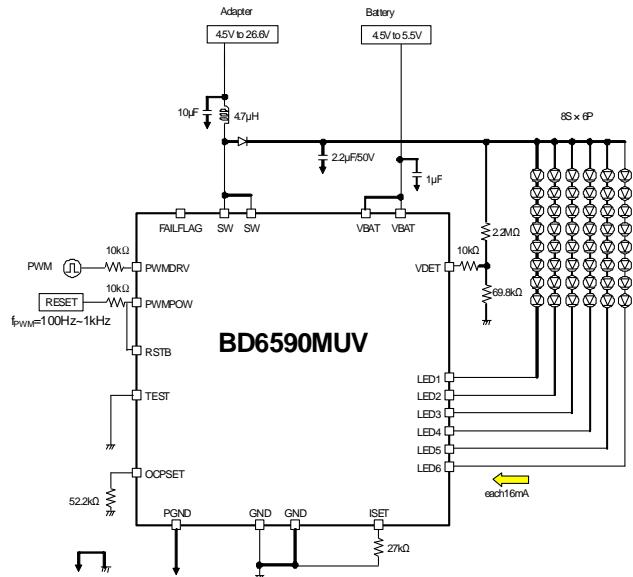


Figure 24. 8series × 6parallel, LED current 16mA,
Switching frequency 1250kHz setting example
Current driver PWM application

10 to 12inch panel

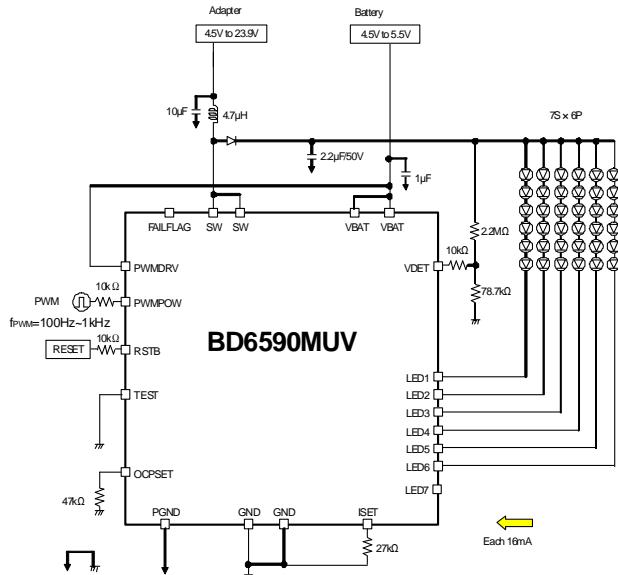


Figure 25. 7series × 6parallel, LED current016mA,
Switching frequency 1250kHz setting example
Power control PWM application

7inch panel

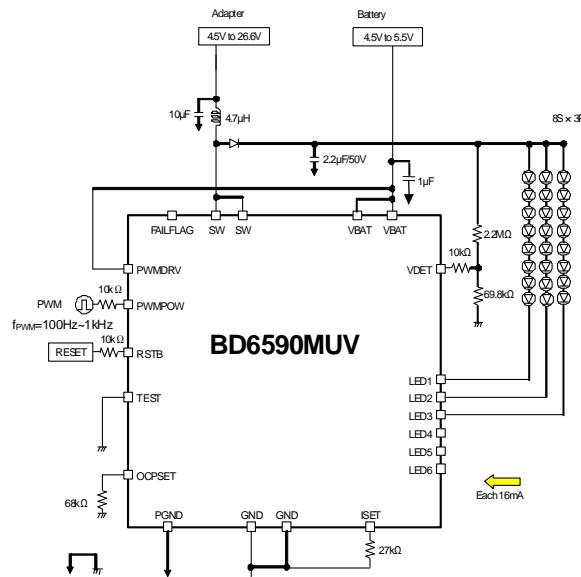


Figure 26. 8series \times 3parallel, LED current 16mA,
Switching frequency 1250kHz setting example
Power control PWM application

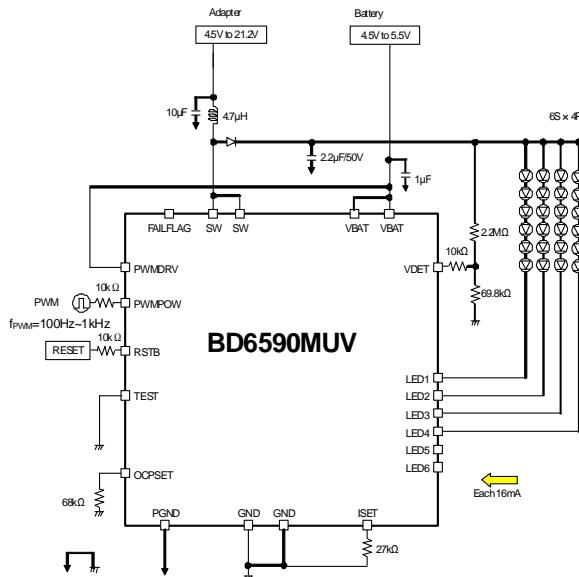


Figure 27. 6series \times 4parallel, LED current 16mA,
Switching frequency 1250kHz setting example
Power control PWM application

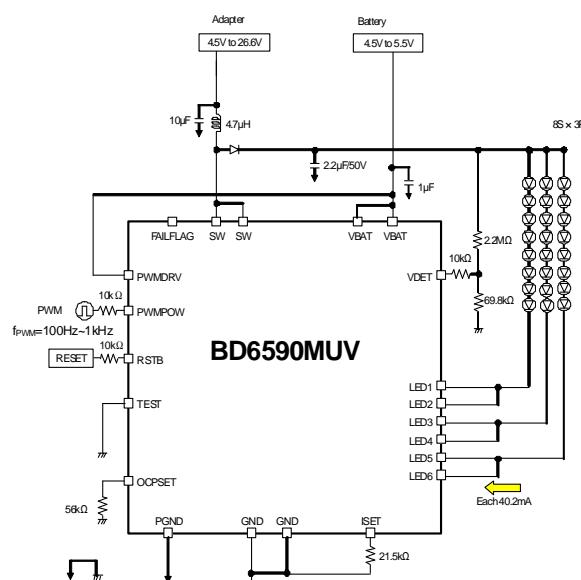


Figure 28. 8series \times 3parallel, LED current 40.2mA,
Switching frequency 1250kHz setting example
Power control PWM application

5inch panel

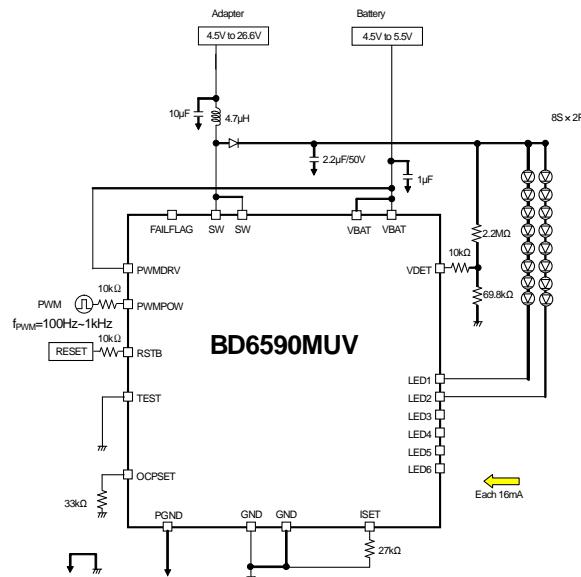


Figure 29. 8series × 2parallel, LED current16mA,
Switching frequency1250kHz setting example
Power control PWM application

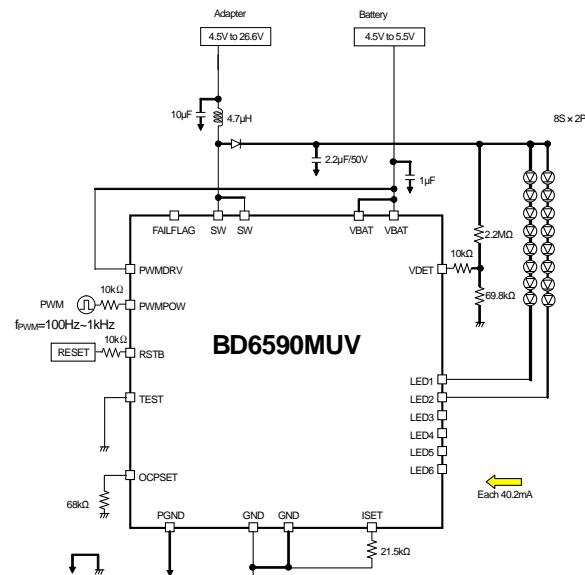


Figure 30. 8series × 2parallel, LED current 40.2mA,
Switching frequency 1250kHz setting example
Power control PWM application

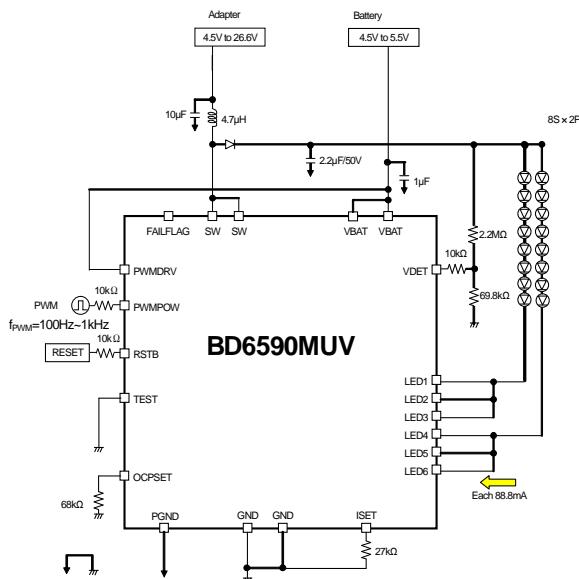


Figure 31. 8series × 2parallel, LED current 88.8mA,
Switching frequency 1250kHz setting example
Power control PWM application

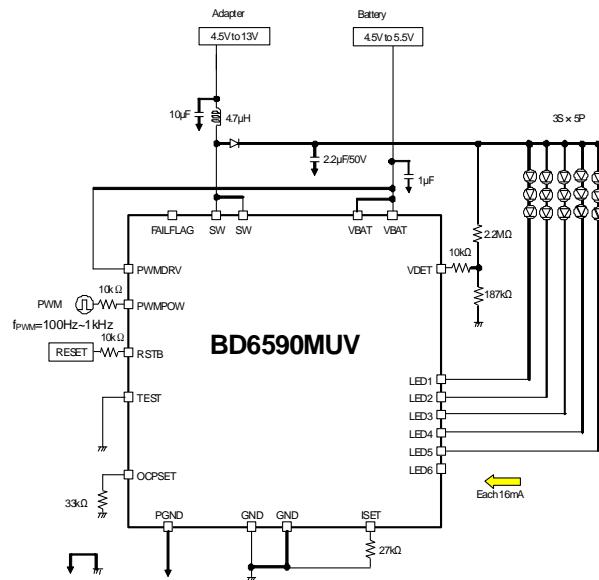


Figure 32. 3series × 5parallel, LED current 16mA,
Switching frequency 1250kHz setting example
Power control PWM application

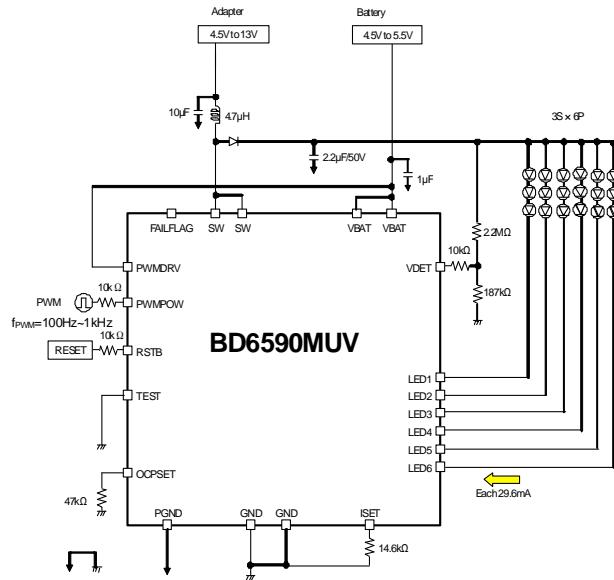


Figure 33. 3series × 6parallel, LED current 29.6mA,
Switching frequency 1250kHz setting example
Power control PWM application

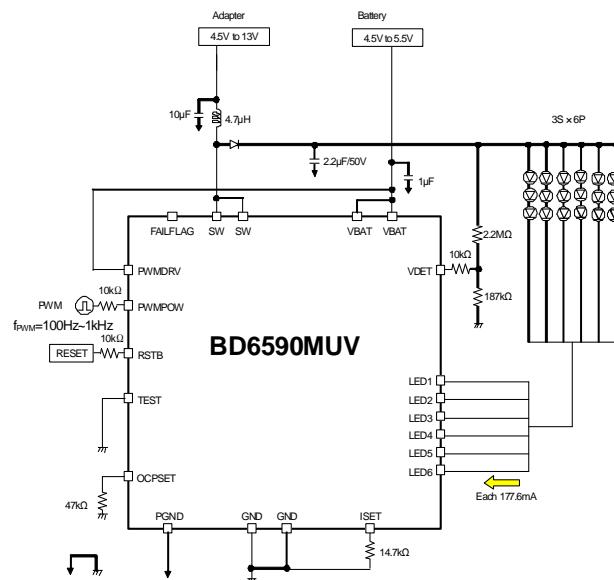


Figure 34. 3series × 6parallel, LED current 177.6mA,
Switching frequency 1250kHz setting example
Power control PWM application

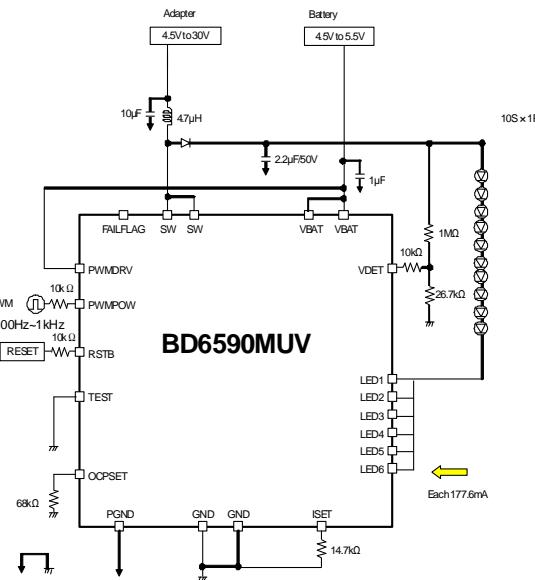


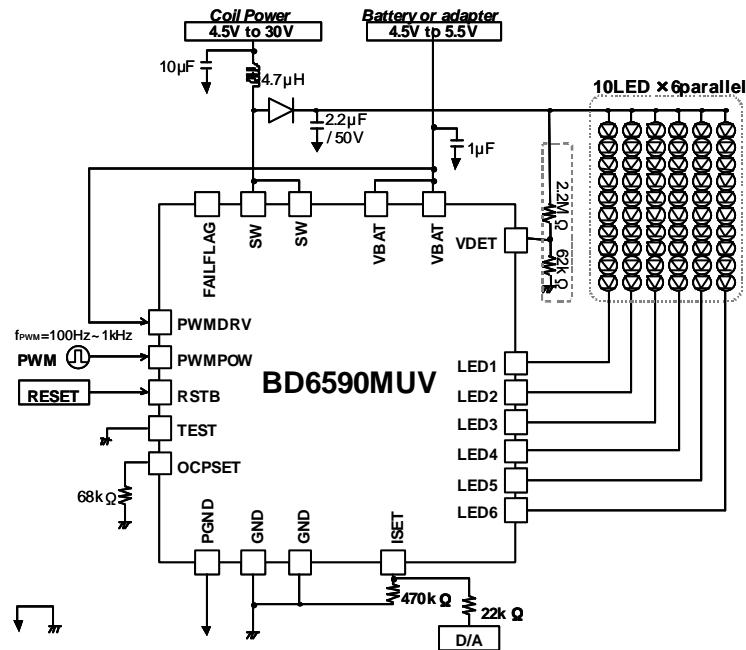
Figure 35. 10series × 1parallel, LED current177.6mA,
Switching frequency 1250kHz setting example
Power control PWM application

● Application Example of Analog Dimming

Control LED current to charged D/A voltage.

Show application example and typ control.

Please decide final value after you evaluated application, characteristic.



$$\text{LEDcurrent} = \frac{432}{470\text{k}\Omega} + \frac{432}{22\text{k}\Omega} \left(1 - \frac{\text{DAC}}{\text{ISETvoltage}} \right)$$

$$\text{typ LEDcurrent} = \frac{432}{470\text{k}\Omega} + \frac{432}{22\text{k}\Omega} \left(1 - \frac{\text{DAC}}{0.6\text{V}} \right)$$

Figure 36. BD6590MUV Analog style optical application

● Operational Notes

(1) Absolute Maximum Ratings

An excess in the absolute maximum ratings, such as supply voltage, temperature range of operating conditions, etc., can break down devices, thus making impossible to identify breaking mode such as a short circuit or an open circuit. If any special mode exceeding the absolute maximum ratings is assumed, consideration should be given to take physical safety measures including the use of fuses, etc.

(2) Operating conditions

These conditions represent a range within which characteristics can be provided approximately as expected. The electrical characteristics are guaranteed under the conditions of each parameter.

(3) Reverse connection of power supply connector

The reverse connection of power supply connector can break down ICs. Take protective measures against the breakdown due to the reverse connection, such as mounting an external diode between the power supply and the IC's power supply terminal.

(4) Power supply line

Design PCB pattern to provide low impedance for the wiring between the power supply and the GND lines. In this regard, for the digital block power supply and the analog block power supply, even though these power supplies has the same level of potential, separate the power supply pattern for the digital block from that for the analog block, thus suppressing the diffraction of digital noises to the analog block power supply resulting from impedance common to the wiring patterns. For the GND line, give consideration to design the patterns in a similar manner.

Furthermore, for all power supply terminals to ICs, mount a capacitor between the power supply and the GND terminal. At the same time, in order to use an electrolytic capacitor, thoroughly check to be sure the characteristics of the capacitor to be used present no problem including the occurrence of capacity dropout at a low temperature, thus determining the constant.

(5) GND voltage

Make setting of the potential of the GND terminal so that it will be maintained at the minimum in any operating state. Furthermore, check to be sure no terminals are at a potential lower than the GND voltage including an actual electric transient.

(7) Short circuit between terminals and erroneous mounting

In order to mount ICs on a set PCB, pay thorough attention to the direction and offset of the ICs. Erroneous mounting can break down the ICs. Furthermore, if a short circuit occurs due to foreign matters entering between terminals or between the terminal and the power supply or the GND terminal, the ICs can break down.

(8) Operation in strong electromagnetic field

Be noted that using ICs in the strong electromagnetic field can malfunction them.

(9) Inspection with set PCB

On the inspection with the set PCB, if a capacitor is connected to a low-impedance IC terminal, the IC can suffer stress. Therefore, be sure to discharge from the set PCB by each process. Furthermore, in order to mount or dismount the set PCB to/from the jig for the inspection process, be sure to turn OFF the power supply and then mount the set PCB to the jig. After the completion of the inspection, be sure to turn OFF the power supply and then dismount it from the jig. In addition, for protection against static electricity, establish a ground for the assembly process and pay thorough attention to the transportation and the storage of the set PCB.

(10) Input terminals

In terms of the construction of IC, parasitic elements are inevitably formed in relation to potential. The operation of the parasitic element can cause interference with circuit operation, thus resulting in a malfunction and then breakdown of the input terminal. Therefore, pay thorough attention not to handle the input terminals, such as to apply to the input terminals a voltage lower than the GND respectively, so that any parasitic element will operate. Furthermore, do not apply a voltage to the input terminals when no power supply voltage is applied to the IC. In addition, even if the power supply voltage is applied, apply to the input terminals a voltage lower than the power supply voltage or within the guaranteed value of electrical characteristics.

(11) Ground wiring pattern

If small-signal GND and large-current GND are provided, It will be recommended to separate the large-current GND pattern from the small-signal GND pattern and establish a single ground at the reference point of the set PCB so that resistance to the wiring pattern and voltage fluctuations due to a large current will cause no fluctuations in voltages of the small-signal GND. Pay attention not to cause fluctuations in the GND wiring pattern of external parts as well.

(12) External capacitor

In order to use a ceramic capacitor as the external capacitor, determine the constant with consideration given to a degradation in the nominal capacitance due to DC bias and changes in the capacitance due to temperature, etc.

(13) Thermal shutdown circuit (TSD)

When junction temperatures become 175°C (typ) or higher, the thermal shutdown circuit operates and turns a switch OFF. The thermal shutdown circuit, which is aimed at isolating the LSI from thermal runaway as much as possible, is not aimed at the protection or guarantee of the LSI. Therefore, do not continuously use the LSI with this circuit operating or use the LSI assuming its operation.

(14) Thermal design

Perform thermal design in which there are adequate margins by taking into account the permissible dissipation (Pd) in actual states of use.

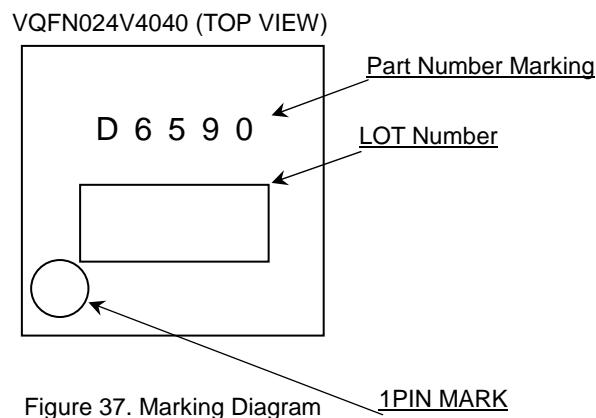
(15) Selection of coil

Select the low DCR inductors to decrease power loss for DC/DC converter.

● Ordering Information

B	D	6	5	9	0	M	U	V	-	E2
Part Number					Package MUV: VQFN024V4040					Packaging and forming specification E2: Embossed tape and reel

● Marking Diagram



● Physical Dimension Tape and Reel Information

VQFN024V4040

<Tape and Reel information>	
Tape	Embossed carrier tape
Quantity	2500pcs
Direction of feed	E2 (The direction is the 1pin of product is at the upper left when you hold reel on the left hand and you pull out the tape on the right hand)
<p>Reel</p> <p>1pin</p> <p>Direction of feed</p> <p>Order quantity needs to be multiple of the minimum quantity.</p>	

Figure 38. VQFN024V4040

● Revision History

Date	Revision	Changes
07.Dec.2012	001	New Release
07.Nov.2016	002	P3 Pin Descriptions add P5 Figure 7 modification P6 Figure 8 modification P11 Reference Page No add

Notice

Precaution on using ROHM Products

1. Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment ^(Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASS III	CLASS III	CLASS II b	CLASS III
CLASS IV		CLASS III	

2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
 - [a] Installation of protection circuits or other protective devices to improve system safety
 - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
3. Our Products are designed and manufactured for use under standard conditions and not under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
 - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
4. The Products are not subject to radiation-proof design.
5. Please verify and confirm characteristics of the final or mounted products in using the Products.
6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
8. Confirm that operation temperature is within the specified range described in the product specification.
9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

Precautions Regarding Application Examples and External Circuits

1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of Ionizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

Precaution for Product Label

A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

Precaution for Disposition

When disposing Products please dispose them properly using an authorized industry waste company.

Precaution for Foreign Exchange and Foreign Trade act

Since concerned goods might be fallen under listed items of export control prescribed by Foreign exchange and Foreign trade act, please consult with ROHM in case of export.

Precaution Regarding Intellectual Property Rights

1. All information and data including but not limited to application example contained in this document is for reference only. ROHM does not warrant that foregoing information or data will not infringe any intellectual property rights or any other rights of any third party regarding such information or data.
2. ROHM shall not have any obligations where the claims, actions or demands arising from the combination of the Products with other articles such as components, circuits, systems or external equipment (including software).
3. No license, expressly or implied, is granted hereby under any intellectual property rights or other rights of ROHM or any third parties with respect to the Products or the information contained in this document. Provided, however, that ROHM will not assert its intellectual property rights or other rights against you or your customers to the extent necessary to manufacture or sell products containing the Products, subject to the terms and conditions herein.

Other Precaution

1. This document may not be reprinted or reproduced, in whole or in part, without prior written consent of ROHM.
2. The Products may not be disassembled, converted, modified, reproduced or otherwise changed without prior written consent of ROHM.
3. In no event shall you use in any way whatsoever the Products and the related technical information contained in the Products or this document for any military purposes, including but not limited to, the development of mass-destruction weapons.
4. The proper names of companies or products described in this document are trademarks or registered trademarks of ROHM, its affiliated companies or third parties.

General Precaution

1. Before you use our Products, you are requested to carefully read this document and fully understand its contents. ROHM shall not be in any way responsible or liable for failure, malfunction or accident arising from the use of any ROHM's Products against warning, caution or note contained in this document.
2. All information contained in this document is current as of the issuing date and subject to change without any prior notice. Before purchasing or using ROHM's Products, please confirm the latest information with a ROHM sales representative.
3. The information contained in this document is provided on an "as is" basis and ROHM does not warrant that all information contained in this document is accurate and/or error-free. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties resulting from inaccuracy or errors of or concerning such information.

BD6590MUV - Web Page[Distribution Inventory](#)

Part Number	BD6590MUV
Package	VQFN024V4040
Unit Quantity	2500
Minimum Package Quantity	2500
Packing Type	Taping
Constitution Materials List	inquiry
RoHS	Yes